

Darlington Transistor

NPN Silicon

MMBT6427LT1G, SMMBT6427LT1G

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	40	Vdc
Collector - Base Voltage	V _{CBO}	40	Vdc
Emitter - Base Voltage	V _{EBO}	12	Vdc
Collector Current - Continuous	Ic	500	mAdc

THERMAL CHARACTERISTICS

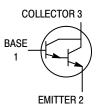
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



SOT-23 (TO-236) CASE 318 STYLE 6



MARKING DIAGRAM



1V = Device Code M = Date Code* ■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT6427LT1G	SOT-23 (Pb-Free)	3,000 Tape & Reel
SMMBT6427LT1G	SOT-23 (Pb-Free)	3,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (I _C = 10 mAdc, V _{BE} = 0)	V _{(BR)CEO}	40	-	Vdc
Collector – Base Breakdown Voltage ($I_C = 100 \mu Adc, I_E = 0$)	V _{(BR)CBO}	40	-	Vdc
Emitter – Base Breakdown Voltage ($I_C = 10 \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	12	-	Vdc
Collector Cutoff Current (V _{CE} = 25 Vdc, I _B = 0)	I _{CES}	-	1.0	μAdc
Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0)	Ісво	-	50	nAdc
Emitter Cutoff Current (V _{EB} = 10 Vdc, I _C = 0)	I _{EBO}	-	50	nAdc
ON CHARACTERISTICS				
DC Current Gain	h _{FE}	10,000 20,000 14,000	100,000 200,000 140,000	-
Collector – Emitter Saturation Voltage (I_C = 50 mAdc, I_B = 0.5 mAdc) (I_C = 500 mAdc, I_B = 0.5 mAdc)	V _{CE(sat)} ⁽³⁾	- -	1.2 1.5	Vdc
Base – Emitter Saturation Voltage ($I_C = 500$ mAdc, $I_B = 0.5$ mAdc)	V _{BE(sat)}	-	2.0	Vdc
Base – Emitter On Voltage (I _C = 50 mAdc, V _{CE} = 5.0 Vdc)	V _{BE(on)}	-	1.75	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)	C _{obo}	-	7.0	pF
Input Capacitance (V _{EB} = 0.5 Vdc, I _C = 0, f = 1.0 MHz)	C _{ibo}	-	15	pF
Current Gain – High Frequency (I _C = 10 mAdc, V _{CE} = 5.0 Vdc, f = 100 MHz)	h _{fe}	1.3	_	Vdc
Noise Figure (I _C = 1.0 mAdc, V_{CE} = 5.0 Vdc, R_S = 100 k Ω , f = 1.0 kHz)	NF	-	10	dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width = $300 \mu s$, Duty Cycle = 2.0%.

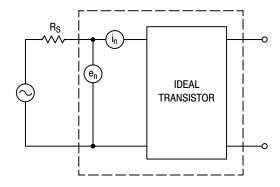


Figure 1. Transistor Noise Model

NOISE CHARACTERISTICS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C})$

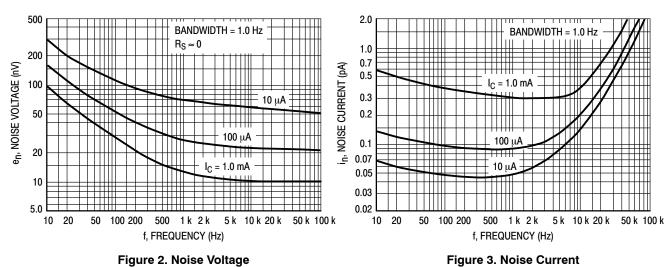


Figure 2. Noise Voltage

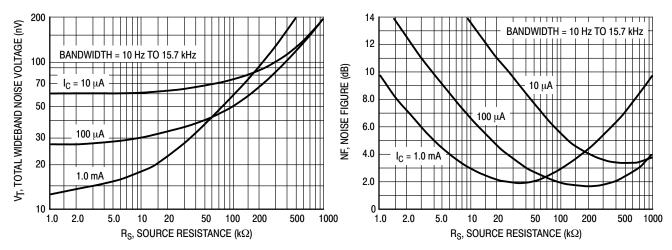
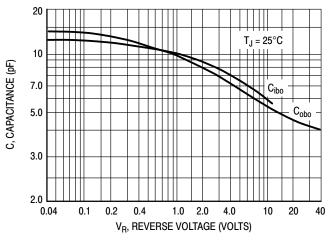


Figure 4. Total Wideband Noise Voltage

Figure 5. Wideband Noise Figure

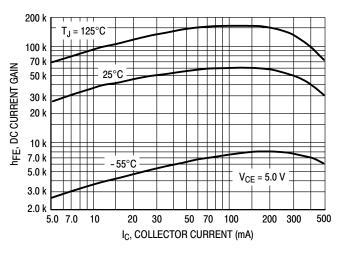
SMALL-SIGNAL CHARACTERISTICS



 $V_{CE} = 5.0 V$ hfel, SMALL-SIGNAL CURRENT GAIN f = 100 MHz $T_J = 25^{\circ}C$ 2.0 1.0 0.8 0.6 0.4 0.2 2.0 20 50 100 200 500 1.0 0.5 10 0.5 IC, COLLECTOR CURRENT (mA)

Figure 6. Capacitance

Figure 7. High Frequency Current Gain



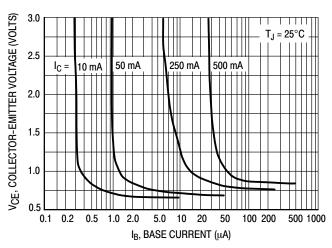
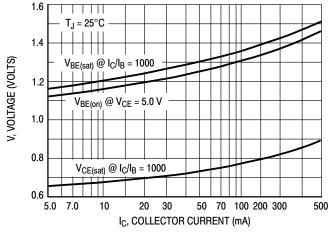


Figure 8. DC Current Gain

Figure 9. Collector Saturation Region



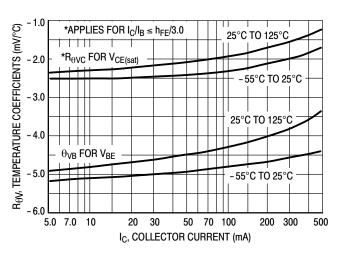


Figure 10. "On" Voltages

Figure 11. Temperature Coefficients

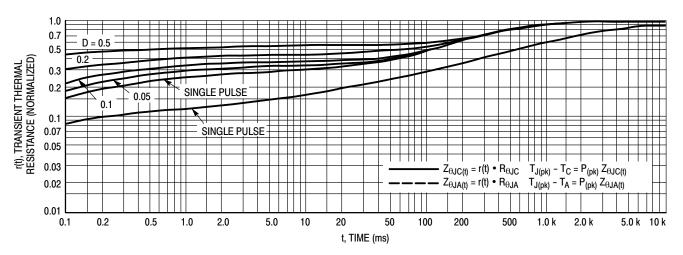
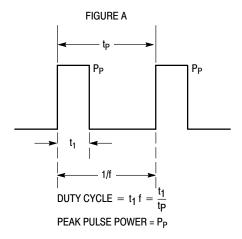


Figure 12. Thermal Response



Design Note: Use of Transient Thermal Resistance Data

MILLIMETERS

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40





SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

DATE 14 AUG 2024

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°





DETAIL "A" Scale 3:1







NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR			
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	2. CATHODE 2.	2: STYLE 13: CATHODE PIN 1. SOURCE CATHODE 2. DRAIN ANODE 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	2. ANODE 2.	3: STYLE 19: NO CONNECTION PIN 1. CATHODE CATHODE 2. ANODE ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT			STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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